

# ESDA14V2BP6

# Application Specific Discretes A.S.D. $^{TM}$

TRANSIL™

#### **MAIN APPLICATIONS**

Where transient overvoltage protection in ESD sensitive equipment is required, such as :

- Computers
- Printers
- Communication systems and cellular phones
- Video equipment

This device is particularly adpated to the protection of symmetrical signals.

#### **FEATURES**

- 4 Bidirectional Transil<sup>™</sup> functions.
- ESD Protection: IEC61000-4-2 level 4
- Stand off voltage: 12V MIN
- Low leakage current < 1µA

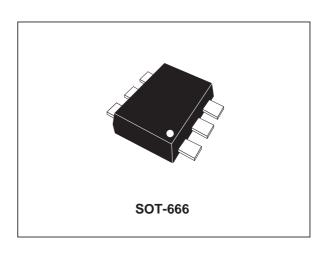
#### **DESCRIPTION**

The ESDA14V2BP6 is a monolithic array designed to protect up to 4 lines in a bidirectional way against ESD transients.

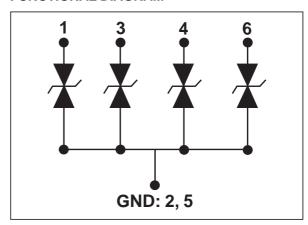
This device is ideal for applications where board space saving is required.

#### **BENEFITS**

- High ESD protection level.
- High integration.
- Suitable for high density boards.



## **FUNCTIONAL DIAGRAM**



#### **COMPLIES WITH THE FOLLOWING STANDARDS:**

- IEC61000-4-2 level 4: 15 kV (air discharge) 8 kV (contact discharge)
- MIL STD 883E-Method 3015-7: class 3 25kV HBM (Human Body Model)

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# ESDA14V2BP6

# **ABSOLUTE RATINGS** $(T_{amb} = 25^{\circ}C)$

Symbol	Parameter Test conditions		Value	Unit
V <sub>PP</sub>	ESD discharge - IEC61000-4 IEC61000-4	± 15 ± 8	kV	
P <sub>PP</sub>	Peak pulse power dissipation	50	W	
Tj	Junction temperature	125	°C	
T <sub>stg</sub>	Storage temperature range	- 55 to + 150	°C	
TL	Maximum lead temperature fo	260	°C	
T <sub>op</sub>	Operating temperature range	- 40 to + 125	°C	

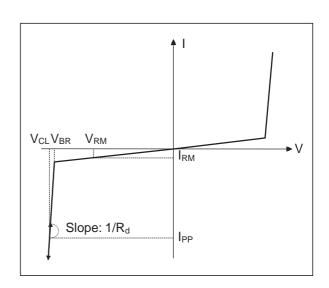
Note 1: for a surge greater than the maximum values, the diode will fail in short-circuit.

## THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R <sub>th(j-a)</sub>	Junction to ambient on printed circuit on recommended pad layout	220	°C/W

# **ELECTRICAL CHARACTERISTICS** (T<sub>amb</sub> = 25°C)

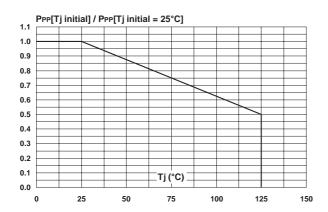
ELLOTRICAL CHARACTERIOTICS (Tallip = 20 0)				
Symbol	Parameter			
V <sub>RM</sub>	Stand-off voltage			
$V_{BR}$	Breakdown voltage			
V <sub>CL</sub>	Clamping voltage			
I <sub>RM</sub>	Leakage current @ V <sub>RM</sub>			
I <sub>PP</sub>	Peak pulse current			
αΤ	Voltage tempature coefficient			
V <sub>F</sub>	Forward voltage drop			



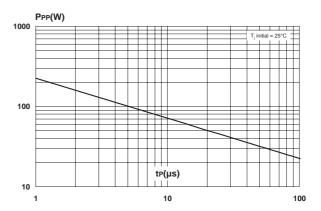
Types	I <sub>RM</sub> @ V <sub>RM</sub>			V <sub>BR</sub> @	<b>I</b> R	Rd	αΤ	С
	max.		min.	max.		typ.	typ.	max.
	μA	V	V	V	mA	Ω	10 <sup>-4</sup> /°C	pF @ 0V
	1	12	14.2	18	1	1.5	5.8	25
ESDA14V2BP6	0.1	3						

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**Fig. 1:** Relative variation of peak pulse power versus initial junction temperature.



**Fig. 2:** Peak pulse power versus exponential pulse duration.



**Fig. 3:** Clamping voltage versus peak pulse current (typical values, rectangular waveform).

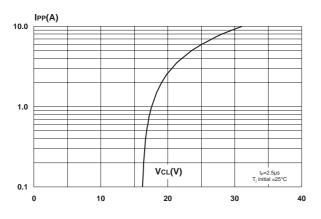
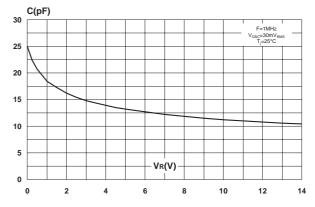
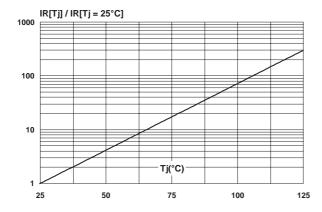


Fig. 4: Junction capacitance versus reverse voltage applied (typical values).

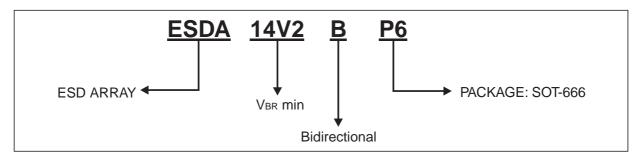


**Fig. 5:** Relative variation of leakage current versus junction temperature (typical values).



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# **ORDER CODE**

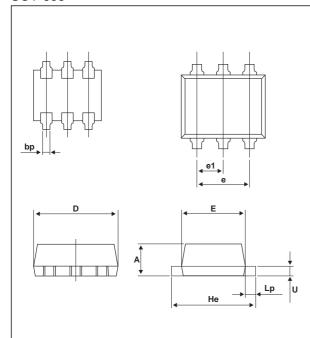


Ordering type	Marking	Package	Weight	Base qty	Delivery mode
ESDA14V2BP6	А	SOT-666	2.9 mg.	3000	Tape & reel 7"

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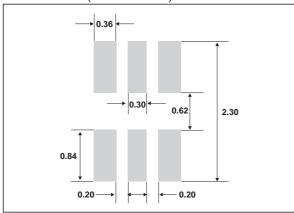
## **PACKAGE MECHANICAL DATA**

SOT-666



	DIMENSIONS						
REF.	Millin	neters	Inches				
	Min.	Max.	Min.	Max.			
Α	0.50	0.60	0.020	0.024			
bp	0.17	0.27	0.007	0.011			
С	0.08	0.18	0.003	0.007			
D	1.50	1.50 1.70		0.067			
E	1.10	1.30	0.043	0.051			
е	1.	00	0.040				
e1	0.50		0.020				
He	1.50	1.70	0.059	0.067			
Lp	0.10	0.30	0.004	0.012			

#### FOOT PRINT (in millimeters)



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